

27-Line SCSI Terminator

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 (Ultra) Standards
- 2.5pF Channel Capacitance during Disconnect
- 100mA Supply Current in Disconnect Mode
- 4V To 7V Operation
- 110 Termination
- Completely Meets SCSI Hot Plugging
- –900mA Sourcing Current for Termination
- +500mA Sinking Current for Active Negation
- Logic Command Disconnects all Termination Lines
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

DESCRIPTION

UCC5620 provides 27 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable.

The UCC5620 is ideal for high performance 5V SCSI systems. During disconnect the supply current is typically only $100\mu A$, which makes the IC attractive for lower powered systems.

The UCC5620 is designed with a low channel capacitance of 2.5pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

The power amplifier output stage allows the UCC5620 to source full termination current and sink active negation current when all termination lines are actively negated.

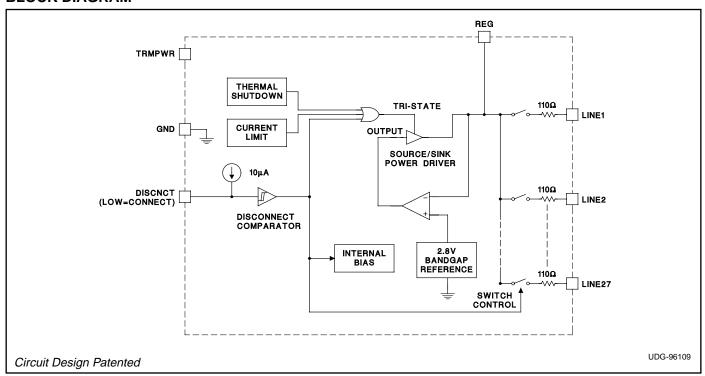
The UCC5620, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the teminating channels with $V_{TRMPWR} = 0V$ or open.

Internal circuit trimming is utilized, first to trim the 110Ω impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in fast SCSI operation.

Other features include thermal shutdown and current limit. This device is offered in low thermal resistance versions of the industry standard 36-Pin Wide Body QSOP (MWP) and 48-Pin LQFP (FQP).

Consult QSOP-36 or LQFP-48 packaging diagram for exact dimensions.

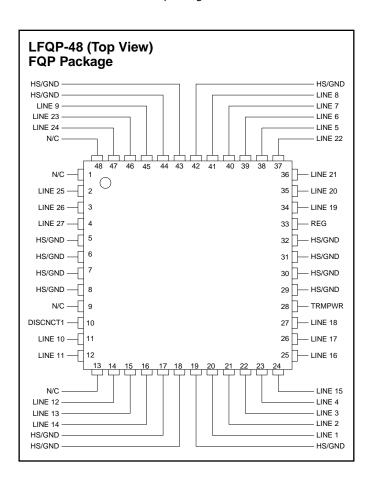
BLOCK DIAGRAM



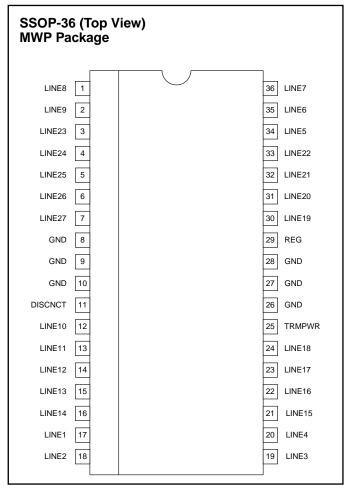
ABSOLUTE MAXIMUM RATINGS

Termpwr Voltage	+7V
Signal Line Voltage	. 0V to +7V
Regulator Output Current	1.5A
Storage Temperature	c to +150°C
Junction Temperature	c to +150°C
Lead Temperature (Soldering, 10 Sec.)	+300°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.



CONNECTION DIAGRAM



ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $T_A = 0$ °C to 70°C, TRMPWR = 4.75V, DISCNCT = 0V, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
Supply Current Section						
TRMPWR Supply Current	All Termination Lines = Open		1	2	mA	
	All Termination Lines = 0.2V		630	650	mA	
Power Down Mode	DISCNCT = TRMPWR		100	200	μΑ	

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $T_A = 0$ °C to 70°C, TRMPWR = 4.75V, DISCNCT = 0V, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS		
Output Section (Termination Lines)							
Termination Impedance	(Note 3)	104.5	110	115.5	Ω		
Output High Voltage	(Note 1)	2.6	2.8	3.0	V		
Max Output Current	$V_{LINE} = 0.2V, T_{J} = 25^{\circ}C$	-22.1	-23.3	-24	mA		
	$V_{LINE} = 0.2V$	-20.7	-23.3	-24	mA		
	$V_{LINE} = 0.2V$, TRMPWR = 4V, $T_J = 25$ °C (Note 1)	-21	-23	-24	mA		
	V _{LINE} = 0.2V, TRMPWR = 4V (Note 1)	-20	-23	-24	mA		
	$V_{LINE} = 0.5V$			-22.4	mA		
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0V to 5.25V		10	400	nA		
Output Capacitance	DISCNCT = 2.4V (Note 2)		2.5	4	pF		
Regulator Section							
Regulator Output Voltage		2.6	2.8	3.0	V		
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V		
Short Circuit Current	$V_{REG} = 0V$	-650	-900	-1300	mA		
Sinking Current Capability	$V_{REG} = 3.5V$	300	500	900	mA		
Thermal Shutdown			170		C°		
Thermal Shutdown Hysteresis			10		C°		
Disconnect Section							
Disconnect Threshold		0.8	1.5	2.0	V		
Input Current	DISCNCT = 0V		-20	-60	μΑ		

Note 1: Measuring each termination line while other 26 are low (0.2V).

Note 2:Guaranteed by design. Not 100% tested in production.

Note 3: Tested by measuring I_{OUT} with $V_{OUT} = 0.2V$ and V_{OUT} with no load, then calculate: $Z = \frac{\left(V_{OUT} \ N.L. - 0.2V\right)}{I_{OUT} \ at \ 0.2V}$

PIN DESCRIPTIONS

DISCNCT: Taking this pin high or leaving it open causes all channels to become high impedance, and the chip to go into low-power mode; a low state allows the channels to provide normal termination.

GND: Ground reference for the IC.

LINE1 - LINE27: 110Ω termination channels.

REG: Output of the internal 2.7V regulator.

TRMPWR: Power for the IC.

APPLICATION INFORMATION

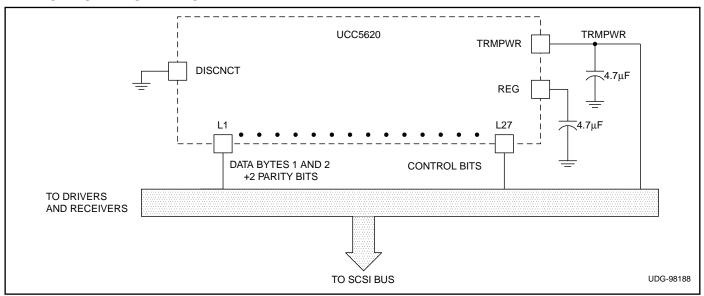


Figure 1. Typical Wide SCSI Bus Configuration Using the UCC5620

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 2000, Texas Instruments Incorporated